DATA SHEET

SUNGMUN CODE : GSPR-10S (LG)

DESCRIPTION : MINI ROTARY DIP SWITCH

SUNGMUN ELECTRONICS CO., LTD.

Address 301-302, Bucheon Technopark 345, Seokcheon-ro, Ojeong-gu

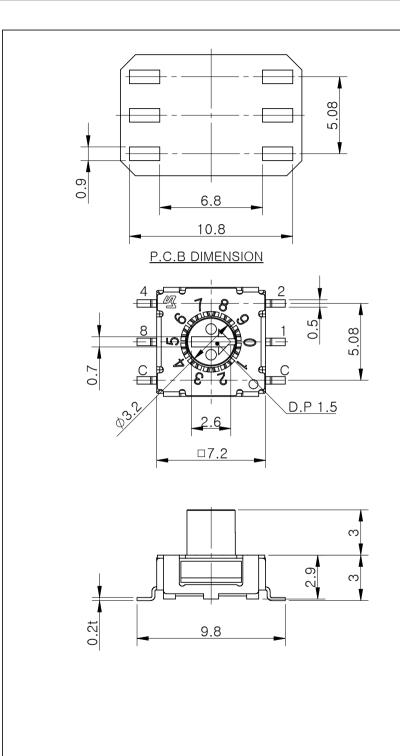
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MRK.	DATE	REVISION	SIGN
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Specification

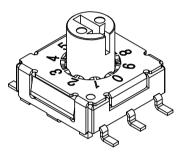
1. Rating: 100mA, DC 50V(Switching)

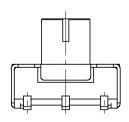
100mA, DC 50V(None-Switching)

2. Contact Resistance : $100m\Omega$ Max 3. Insulation Resistance : $100M\Omega$ Min

4. Operating Force : 200gf Max

5. Life cycle : 10,000 steps 6. Sealing : Comparable IP67





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STANDARD LAYOUT

01	01 COMPACT ROTARY SWITCH			재질 〈지정안함〉		1	-			
NO.	NO. DESCRIPTION			MATERIAL COLOR/FINISH		Q,TY	VEND	OR		
DRAW/D	ESIGNED	CHECKED	APPROVED	Ф	G.TOL	TITLE	COMPACT DOTADY CWITCH			
					±0.1	IIILE	COMPACT ROTARY SWITCH			
				UNIT	SCALE	MODEL	GSPR-10S (LG	`		CHEET
2020-1	1-09			mm	4:1	MODEL	GSPN-103 (LG)		SHEET	
SI.	SUNGMUN ELECTRONICS CO.,LTD					DRAW	GSPR-10S (LG	Α		1/1
30	SUNGMUN ELECTRONICS CO.,LID				A4	NO.	G950-109 (FG	ı)		1/1



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1. Style:

This specification describes "Compact Mini Rotary Dip Switch" which is G series.

1.1 Operating / Storage Temperature Range : -40°C ~ +85°C

2. Rating:

2.1 None-Switching: 100 mA, DC 50V 2.2 Switching: 100 mA, DC 5V

3. Type of Actuation : Rotating

4. Electrical Characteristics

ITEM	DESCRIPTION	TEST CONDITIONS	REQUIREMENTS
4-1	Visual Examination	By visual examination check without any out pressure & testing.	There shall be no defects that affect the serviceability of the product.
4-2	Contact Resistance	 To be measured between the two terminals associated with each switch pole. Measurements shall be made with a 1kHz shall current contact resistance meter. 	100mΩ max. (initial)
4-3	Insulation Resistance	100V DC	100 MΩ min.
4-4	Dielectric withstanding Voltage	250V AC(50Hz or 60Hz)shall be applied between all the adjacent terminal and between the terminal and the frame for 1 minute.	There shall be no breakdown or flashover.



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5. Mechanical Characteristics

ITEM	DESCRIPTION	TEST CONDITIONS	REQUIREMENTS
5-1	Operation Force	Operating direction shall be clockwise or counter clockwise direction	200gf•cm max (1.96N•cm max)
5-2	Operation Life	Measurements shall be made following the test set forth below: 1)100mA, 5V DC resistive load 2)Rate of operation: 15~20 cycles/ minute 3)Step of operation: 10,000 steps	1)As shown in item 3,4 2)Contact Resistance: 200mΩ max 3)Final-after test

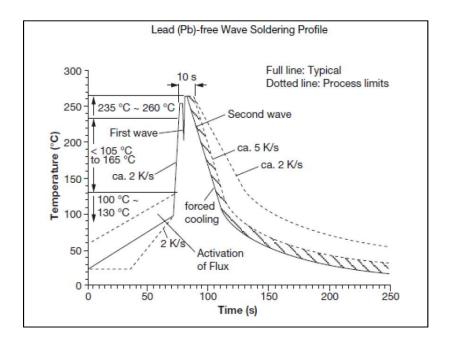
6. Environmental Characteristics

ITEM	DESCRIPTION	TEST CONDITIONS	REQUIREMENTS
6-1	Resistance Low Temperature	Following the test set forth below the sample shall be left in normal temperature and humidity conditions for an hour before measurements are made: 1)Temperature: -40°C ±3°C 2)Time: 96 hours	1)As shown in item 4-3, 4-4, 5-1 2)Contact Resistance: 200mΩ max
6-2	Resistance High Temperature High Temperature High Temperature Temperature Following the test set forth below the sample shall be left in normal temperature and humidity conditions for an hour before measurements are made: 1)Temperature: 85°C ±2°C 2)Time: 96 hours		1)As shown in item 4-3, 4-4, 5-1 2)Contact Resistance: 200mΩ max
6-3	Resistance Humidity	Following the test set forth below the sample shall be left in normal temperature and humidity conditions for an hour before measurements are made: 1)Temperature: 40°C ±2°C 2)Relative humidity: 90~95% 3)Time: 240 hours	1)As shown in item 4-4, 5-1 2)Contact Resistance: 200mΩ max 3)Insulation Resistance: 10 MΩ min

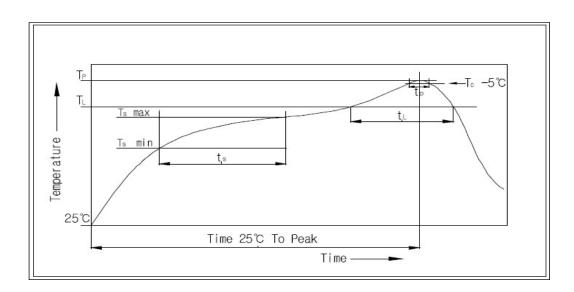


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- 7. This item is "RoHS" Compliant
- 8. Manual Soldering: Max 350°C, 3 sec.
- 9. Wave Soldering Conditions:



10. Reflow Soldering Conditions:





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10-1 Condition for Soldering

Profile Feature	Pb-Free Assembly		
Average Ramp-UP Rate(Ts max to TP)	3°C/second max		
Preheat			
- Temperature Min(Ts min)	150℃		
- Temperature Max(Ts max)	200℃		
- Time (ts min to ts max)	60-180seconds		
Time maintained above:			
- Temperature (TL)	217℃		
- Time (tL)	60-150seconds		
Peak/Classification Temperature(TP)	260°C +0°C/ -5°C		
Time within 5°C of actual Peak Temperature(TP)	5~10 seconds		
Ramp-Down Rate	6°C/sec max		
Time 25℃ to Peak Temperature	8 minutes max		